# SD101AWS THRU SD101CWS



# **Small Signal Schottky Diode**

## Features

- V<sub>R</sub> 60V/50V/40V
- I<sub>FAV</sub> 70mA

#### **Mechanical Data**

- Package: SOD323
- Terminals: Tin plated leads, solderable per
- J-STD-002 and JESD22-B102
- Polarity: Cathode line denotes the cathode end

	Marking
SD101AWS	S1
SD101BWS	S2
SD101CWS	S3

## ■Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VAI	JUE
				SD101AWS	60
Reverse voltage	VR	V	I <sub>R</sub> =10uA	SD101BWS	50
-				SD101CWS	40
Average forward current	IFAV	mA	T <sub>c</sub> =25°C	70	
Power dissipation	P <sub>D</sub>	mW		20	00
Maximum junction temperature	Tj	°C		-55 to +125	
Storage temperature range	T <sub>stg</sub>	°C		-55 to +150	
Thermal Resistance Junction to Ambient Air	R <sub>θJA</sub>	°C /W		50	00

## ■Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions		VALUE	
	VF	V	I <sub>F</sub> =1mA, T <sub>A</sub> =25°C		SD101AWS	0.41
					SD101BWS	0.4
Maximum Forward voltage					SD101CWS	0.39
	V <sub>F</sub> V I <sub>F</sub> =15mA		A, T <sub>A</sub> =25°C	1.0		
Maximum Reverse current	I <sub>R</sub>	uA	SD101AWS	V <sub>R</sub> =50V,T <sub>A</sub> =25°C	0.2	
			SD101BWS	V <sub>R</sub> =40V,T <sub>A</sub> =25°C		
			SD101CWS	V <sub>R</sub> =30V,T <sub>A</sub> =25°C		
	V <sub>(BR)</sub>	V	I <sub>R</sub> =10uA		SD101AWS	60
Minimum Breakdown voltage					SD101BWS	50
					SD101CWS	40
Maximum Junction capacitance	CJ	pF	V <sub>R</sub> =1V, f =1MHz 2			

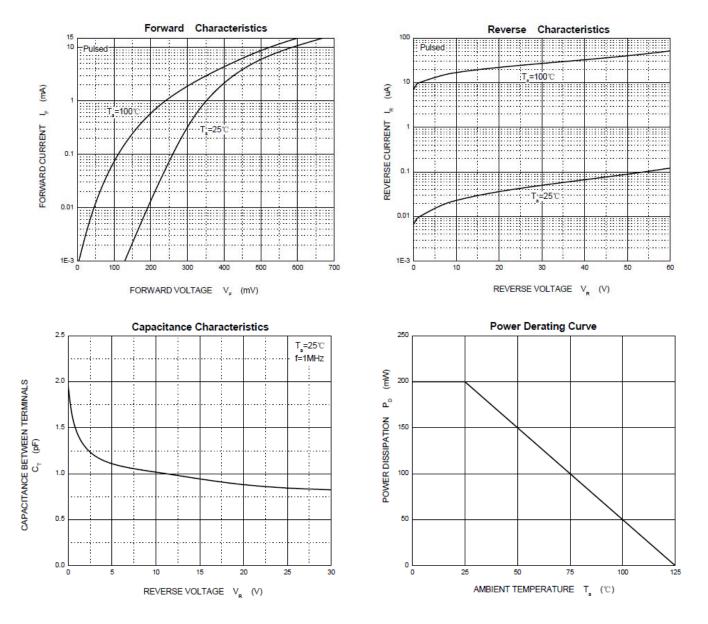
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## ■Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SD101AWS Thru SD101CWS	F2	Approximate 0.0048	3000	30000	120000	7" reel

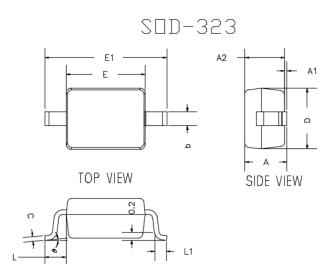
# Characteristics (Typical)



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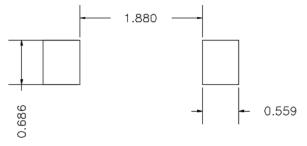
## Outline Dimensions



		DIMENSIONS			
DIM	INC	HES	ММ		
	MIN	MAX	MN	MAX	
A		0.0393		1.0000	
A1	0.0000	0.0039	0.0000	0.1000	
A2	0.0314	0.0354	0.8000	0.9000	
ю	0.0098	0.0157	0.2500	0.4000	
с	0.0031	0.0059	0.0800	0.1500	
D	0.0472	0.0551	1.2000	1,4000	
E	0.0629	0.0709	1.6000	1.8000	
E1	0.0984	0.1063	2.5000	2.7000	
L	0.018	7TYP	0.475TYP		
L1	0.0098	0.0157	0.250	0.400	
e	0*	8*	0*	8*	

SIDE VIEW

## Soldering Footprint



UNIT: mm SUGGESTED SOLDER PAD LAYOUT



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